Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.070”**



**.070”**

**BACKSIDE IS ANODE**

**Top Material: Al**

**Backside Material: Al/Ti/Ni/Au**

**Bond Pad Size: G = .017 X .019”**

 **K = .019 X .044”**

**Backside Potential: ANODE**

**Mask Ref:**

**APPROVED BY: DK DIE SIZE .070” X .070” DATE: 1/26/22**

**MFG: MICROSEMI THICKNESS .011” P/N: 2N2323**

**DG 10.1.2**

#### Rev B, 7/1